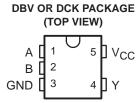
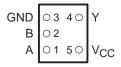
- Available in the Texas Instruments
 NanoStar[™] and NanoFree[™] Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 4 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



description/ordering information

This single 2-input exclusive-OR gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G86 performs the Boolean function $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If the input is low, the other input is reproduced in true form at the output. If the input is high, the signal on the other input is reproduced inverted at the output.

ORDERING INFORMATION

TA	PACKAGET	PACKAGE [†]			
	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA		SN74LVC1G86YEAR		
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)	Reel of 3000	SN74LVC1G86YZAR	СН	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Reel of 3000	SN74LVC1G86YEPR	On_	
−40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC1G86YZPR		
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G86DBVR	C86	
	301 (301-23) = DBV	Reel of 250	SN74LVC1G86DBVT	C80_	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G86DCKR	СН	
	301 (30-10) - DON	Reel of 250	SN74LVC1G86DCKT	OII_	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



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NanoStar and NanoFree are trademarks of Texas Instruments.



description/ordering information (continued)

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

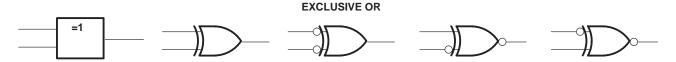
This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE

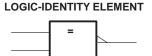
INP	UTS	OUTPUT
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	L

exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.

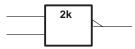


These are five equivalent exclusive-OR symbols valid for an SN74LVC1G86 gate in positive logic; negation may be shown at any two ports.



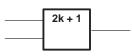
The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT



The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT



The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.



SN74LVC1G86 SINGLE 2-INPUT EXCLUSIVE-OR GATE

SCES222K - APRIL 1999 - REVISED SEPTEMBER 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)† Supply voltage range, V_{CC}–0.5 V to 6.5 V Voltage range applied to any output in the high-impedance or power-off state, Vo (see Note 1)—0.5 V to 6.5 V Voltage range applied to any output in the high or low state, Vo (see Notes 1 and 2)—0.5 V to V_{CC} + 0.5 V Output clamp current, I_{OK} (V_O < 0) –50 mA Continuous output current, IO ±50 mA Continuous current through V_{CC} or GND±100 mA DCK package 252°C/W Storage temperature range, T_{stq} –65°C to 150°C

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V_{CC} is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
\/	Cumply valtage	Operating	1.65	5.5	V
VCC	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
\ <i>/</i>	Lligh level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V
VIH	/IH High-level input voltage	V _{CC} = 3 V to 3.6 V			V
		V _{CC} = 4.5 V to 5.5 V	0.7 × V _{CC}		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
V/	Law layed input valtage	V _{CC} = 2.3 V to 2.7 V		0.7	V
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V
		V _{CC} = 4.5 V to 5.5 V		0.3 × V _{CC}	
٧ _I	Input voltage	•	0	5.5	V
٧o	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-8	
IOH	High-level output current	V 2V		-16	mA
		VCC = 3 V		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I_{OL}	Low-level output current	V 2V		16	mA
		VCC = 3 V		24	
		V _{CC} = 4.5 V		32	
		V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
$\Delta t/\Delta v$	Input transition rise or fall rate	V _{CC} = 3.3 V ± 0.3 V		10	ns/V
		V _{CC} = 5 V ± 0.5 V		5	
TA	Operating free-air temperature	·	-40	85	°C

NOTE 4: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT
	$I_{OH} = -100 \mu\text{A}$	1.65 V to 5.5 V	V _{CC} -0.1			
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
Vou	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			V
VOH	$I_{OH} = -16 \text{ mA}$	3 V	2.4			V
	I _{OH} = -24 mA	3 V	2.3			
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8			
	I _{OL} = 100 μA	1.65 V to 5.5 V			0.1	
	I _{OL} = 4 mA	1.65 V			0.45	
\/a.	I _{OL} = 8 mA	2.3 V			0.3	V
VOL	I _{OL} = 16 mA	3 V			0.4	V
	I _{OL} = 24 mA	3 V			0.55	
	$I_{OL} = 32 \text{ mA}$	4.5 V			0.55	
I _I A or B input	V _I = 5.5 V or GND	0 to 5.5 V			±5	μΑ
l _{off}	V_I or $V_O = 5.5 V$	0			±10	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	1.65 V to 5.5 V			10	μΑ
ΔlCC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V			500	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		6		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =					V _{CC} :		UNIT	
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	Υ	2.1	9.1	1	4.5	0.6	4	0.8	3.3	ns

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

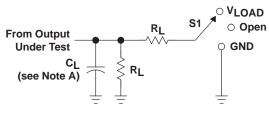
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.		V _{CC} = ± 0.		V _{CC} ± 0.		UNIT
	(1141 01)	(001101)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	A or B	Y	3.5	9.9	1.8	5.5	1.3	5	1	4	ns

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	V _{CC} = 5 V	UNIT	
PARAMETER		TEST CONDITIONS	TYP	TYP TYP		TYP	UNIT	
C _{pd}	Power dissipation capacitance	f = 10 MHz	22	22	22	24	pF	



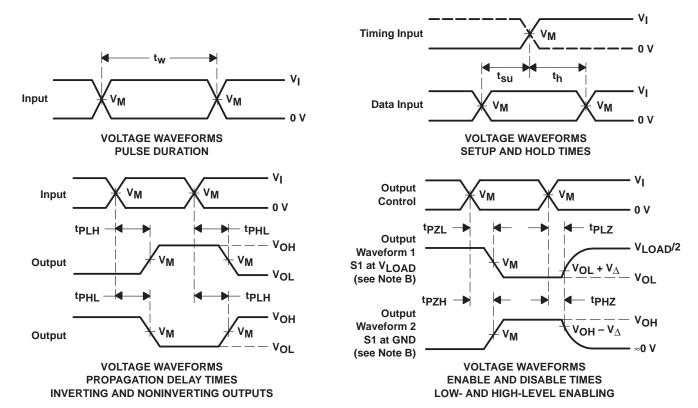
PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LOAD CIRCUIT

.,	INF	INPUTS		.,	•	_	.,
VCC	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	V_Δ
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	15 pF	1 Μ Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	1 Μ Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	15 pF	1 M Ω	0.3 V

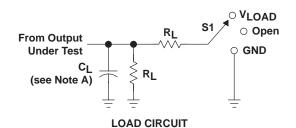


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

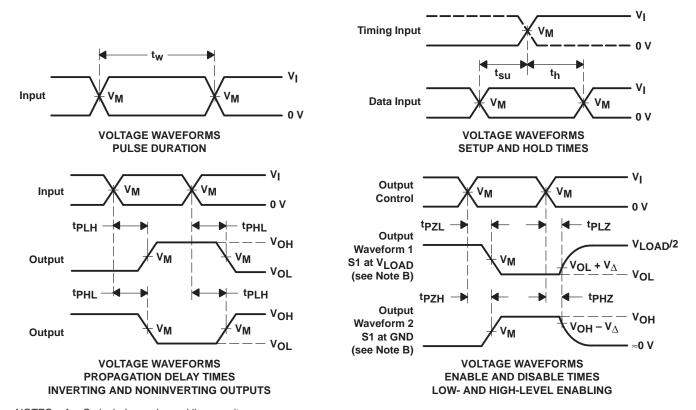


PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

.,	INF	PUTS		V		_	.,
Vcc	٧ _I	t _r /t _f	VM	VLOAD	CL	RL	$oldsymbol{V}_\Delta$
1.8 V ± 0.15 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V \pm 0.5 V	VCC	≤2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

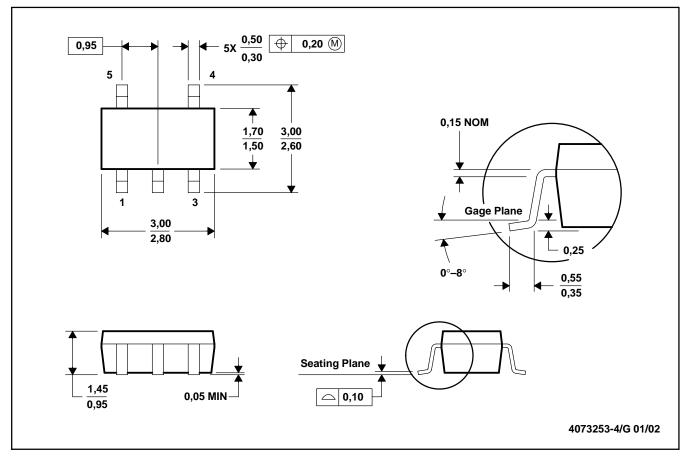
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE

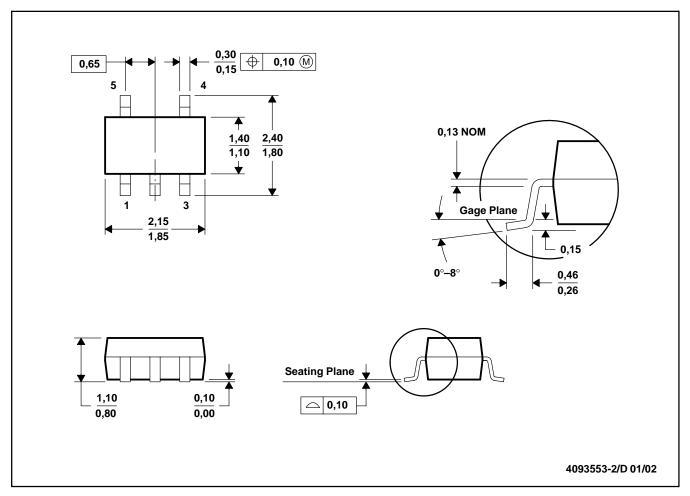


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

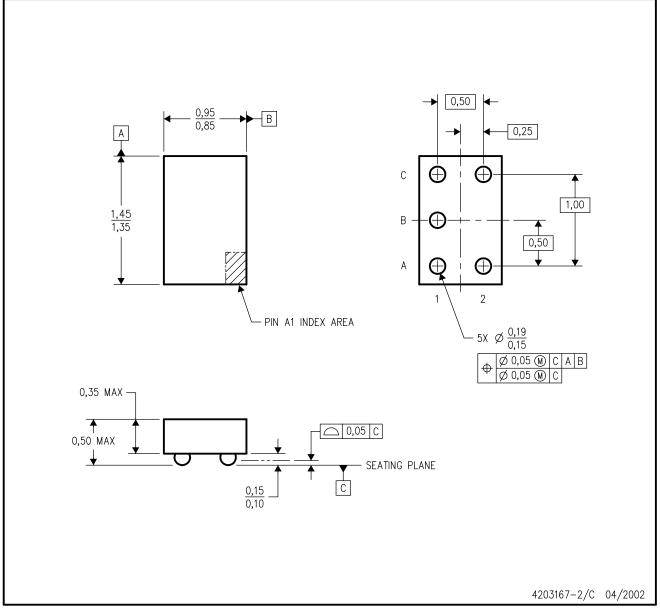
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

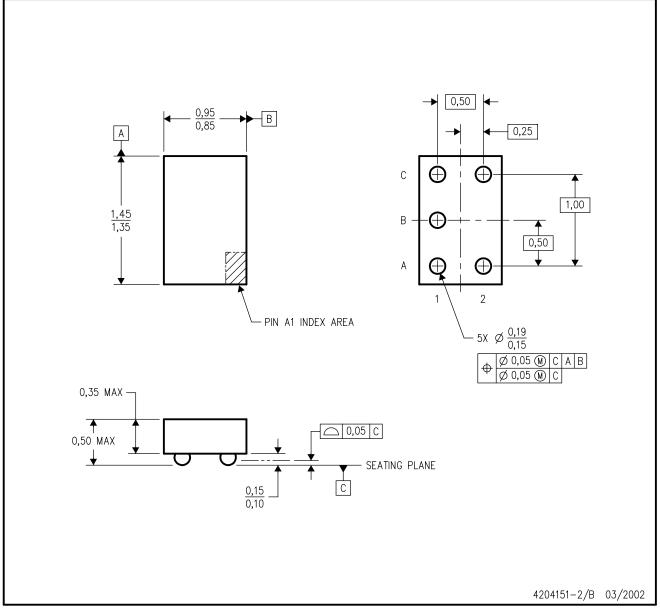
- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

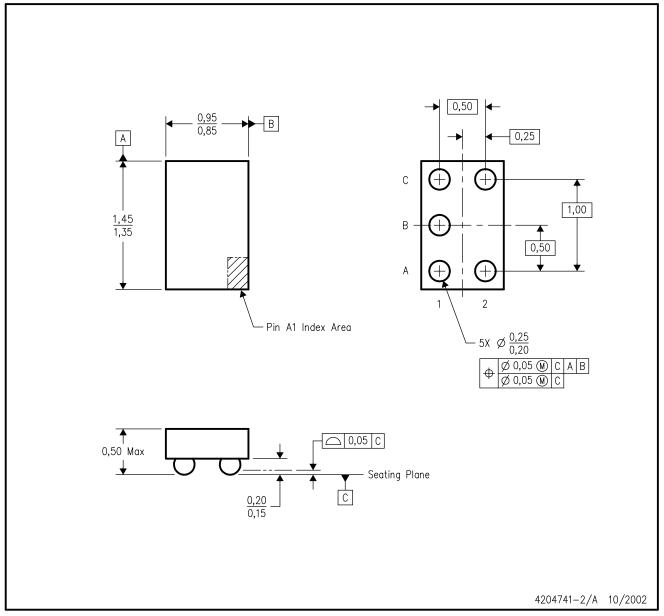
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

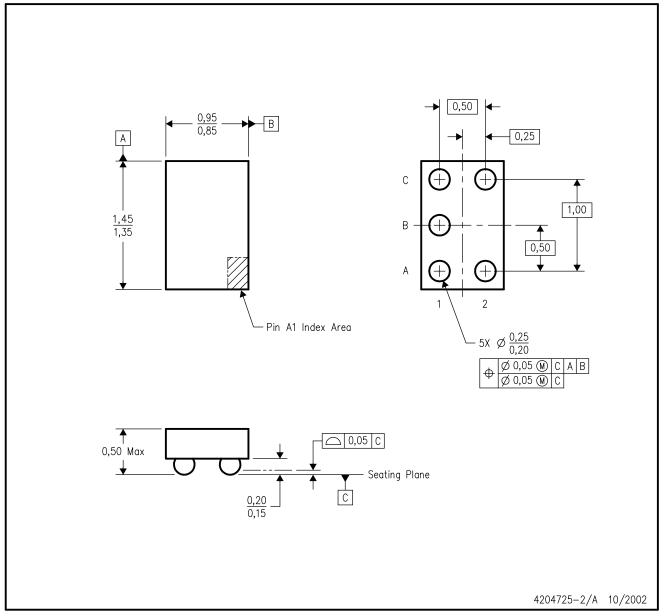
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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